Thermal Characteristics

Package	I_D (continuous)†	I_D (pulsed)	Power Dissipation @T_C = 25°C	I_{DR} †	I_{DRM}
TO-92	50mA	250mA	1.0W	50mA	250mA

Notes:

† I_D *(continuous) is limited by max rated* T_j .

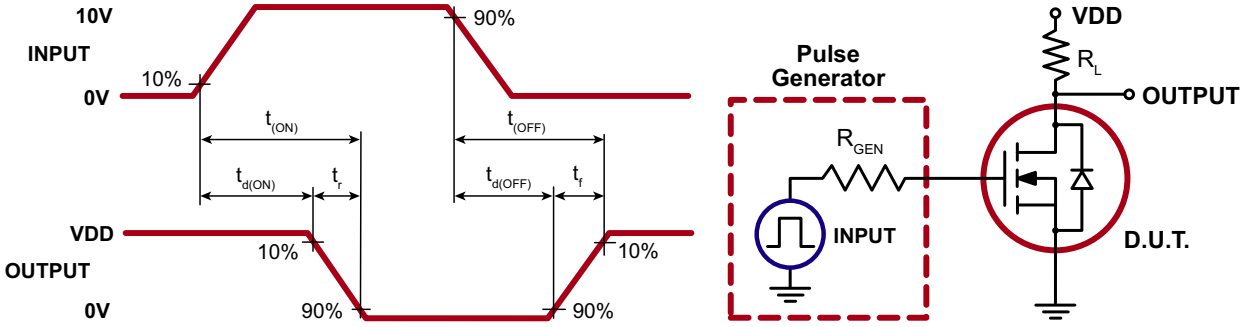
Electrical Characteristics *(T_A = 25°C unless otherwise specified)*

Sym	Parameter	Min	Typ	Max	Units	Conditions
BV_{DSS}	Drain-to-source breakdown voltage	500	-	-	V	V_{GS} = 0V, I_D = 1.0mA
$V_{GS(th)}$	Gate threshold voltage	2.0	-	4.0	V	V_{GS} = V_{DS}, I_D = 1.0mA
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	-3.8	-5.0	mV/°C	V_{GS} = V_{DS}, I_D = 1.0mA
I_{GSS}	Gate body leakage current	-	-	100	nA	V_{GS} = ±20V, V_{DS} = 0V
I_{DSS}	Zero gate voltage drain current	-	-	10	µA	V_{GS} = 0V, V_{DS} = Max Rating
		-	-	1.0	mA	V_{DS} = 0.8 Max Rating, V_{GS} = 0V, T_A = 125°C
$I_{D(ON)}$	On-state drain current	-	100	-	mA	V_{GS} = 5.0V, V_{DS} = 25V
		150	350	-		V_{GS} = 10V, V_{DS} = 25V
$R_{DS(ON)}$	Static drain-to-source on-state resistance	-	45	-	Ω	V_{GS} = 5.0V, I_D = 50mA
		-	40	60		V_{GS} = 10V, I_D = 50mA
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	-	1.0	1.7	%/°C	V_{GS} = 10V, I_D = 50mA
G_{FS}	Forward transconductance	50	100	-	mmho	V_{DS} = 25V, I_D = 50mA
C_{ISS}	Input capacitance	-	45	55	pF	V_{GS} = 0V, V_{DS} = 25V, f = 1.0MHz
C_{OSS}	Common source output capacitance	-	8.0	10		
C_{RSS}	Reverse transfer capacitance	-	2.0	5.0		
$t_{d(ON)}$	Turn-on time	-	-	10	ns	V_{DD} = 25V, I_D = 150mA, R_{GEN} = 25Ω
t_r	Rise time	-	-	15		
$t_{d(OFF)}$	Turn-off time	-	-	10		
t_f	Fall time	-		10		
V_{SD}	Diode forward voltage drop	-	0.8	-	V	V_{GS} = 0V, I_{SD} = 500mA
t_{rr}	Reverse recovery time	-	300	-	ns	V_{GS} = 0V, I_{SD} = 500mA

Notes:

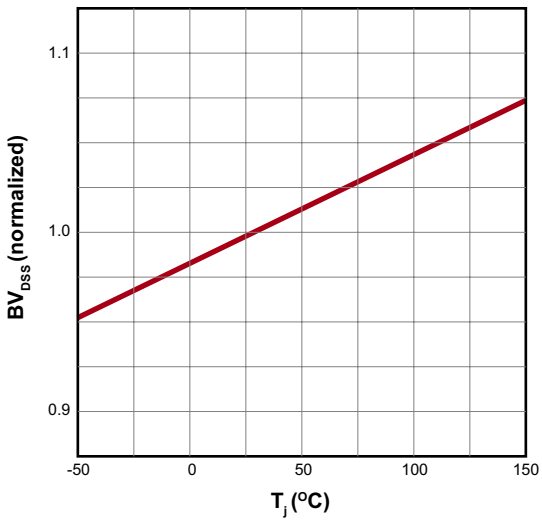
1. *All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)*
2. *All A.C. parameters sample tested.*

Switching Waveforms and Test Circuit

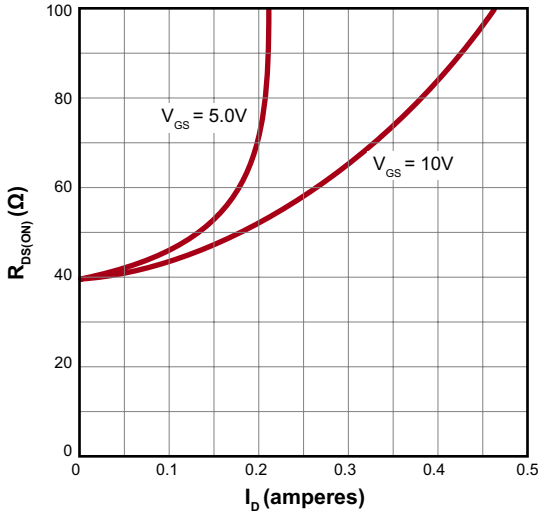


Typical Performance Curves

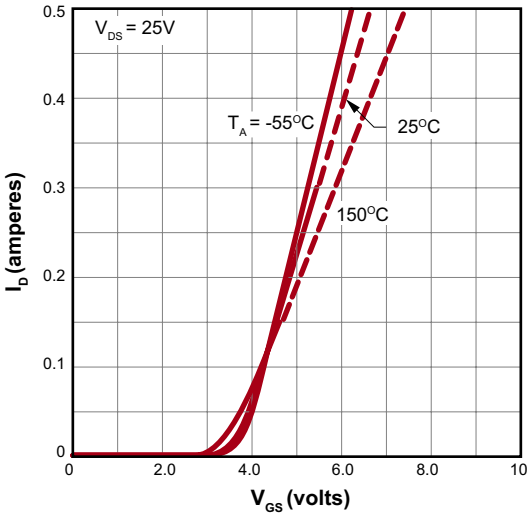
BV_{DSS} Variation with Temperature



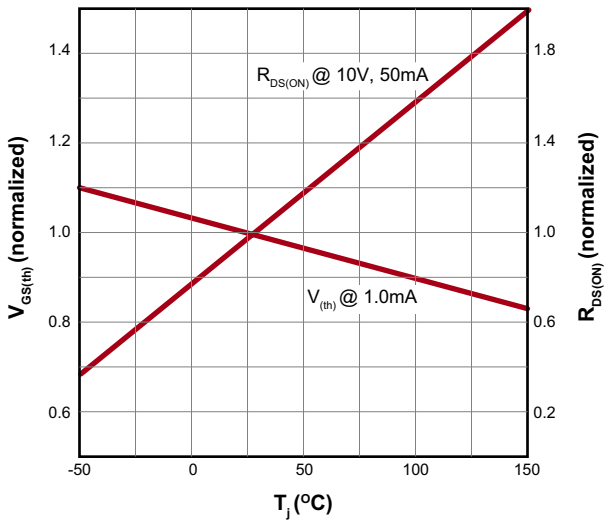
On-Resistance vs. Drain Current



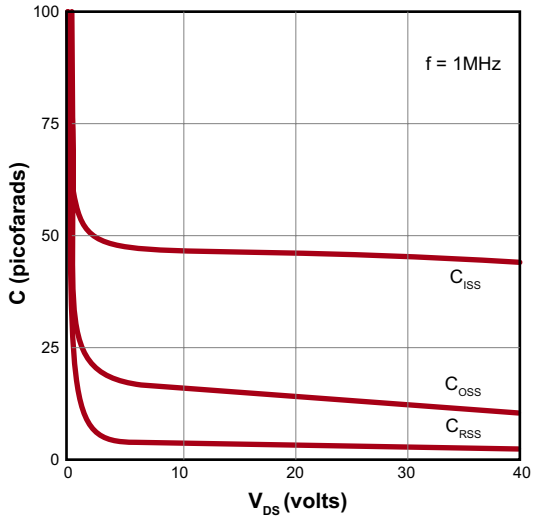
Transfer Characteristics



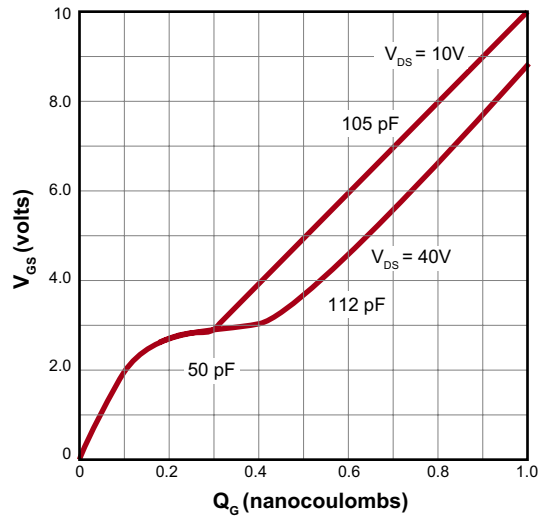
$V_{(th)}$ and R_{DS} Variation with Temperature



Capacitance vs. Drain-to-Source Voltage

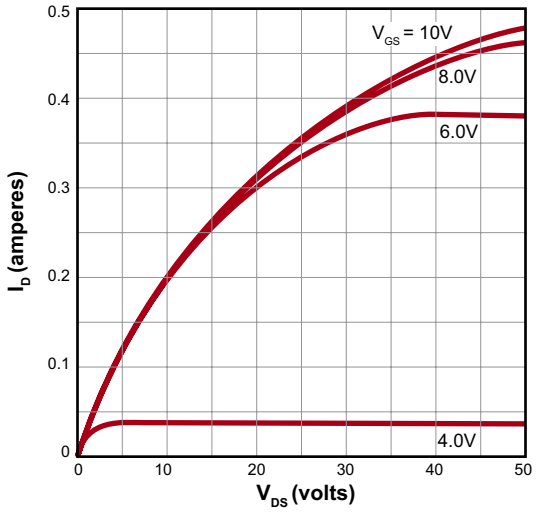


Gate Drive Dynamic Characteristics

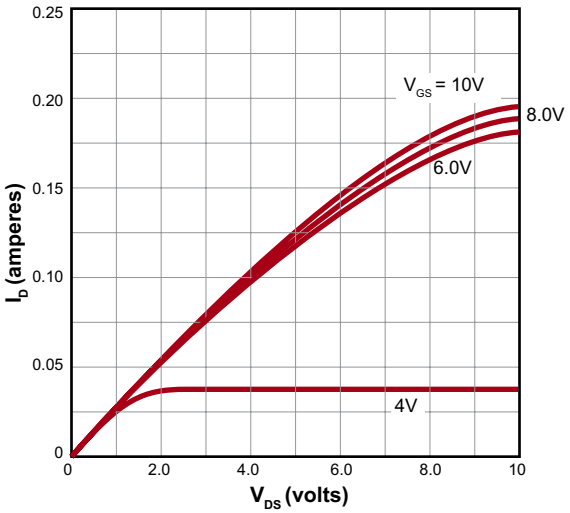


Typical Performance Curves *(cont.)*

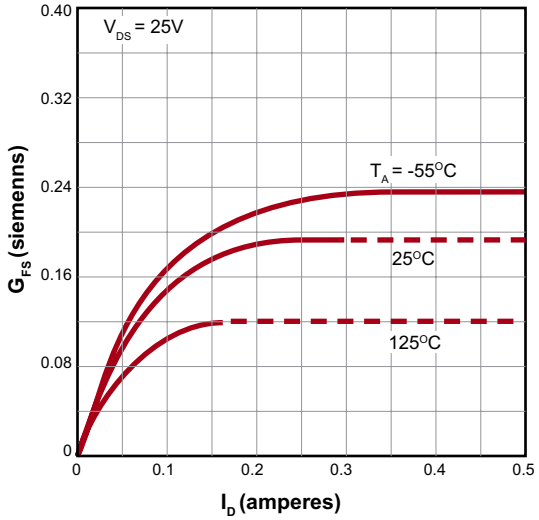
Output Characteristics



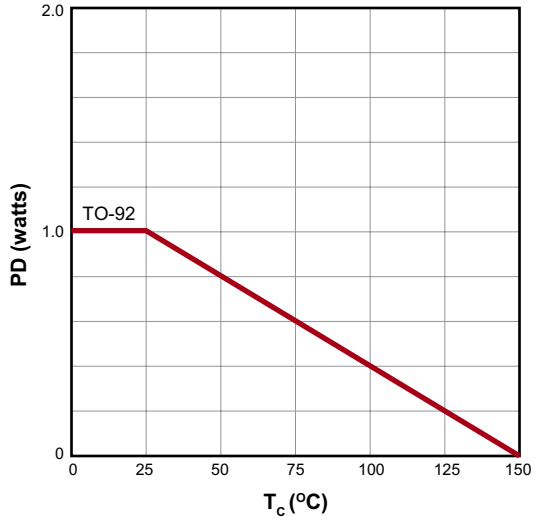
Saturation Characteristics



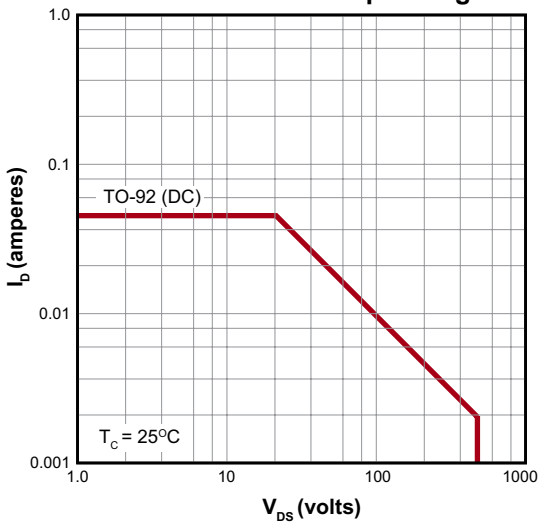
Transconductance vs. Drain Current



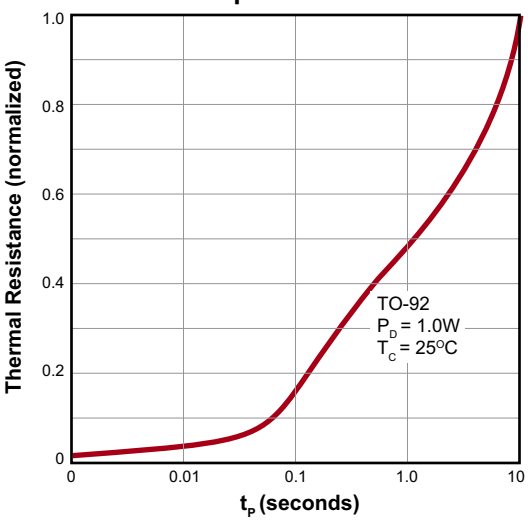
Power Dissipation vs. Case Temperature



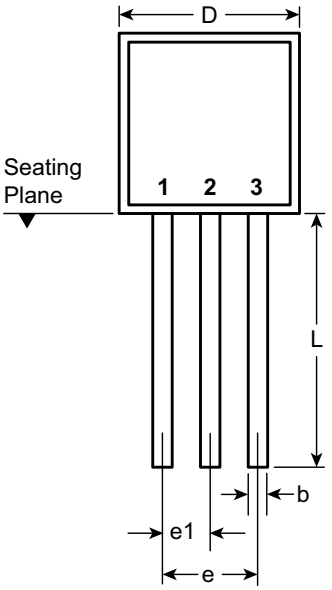
Maximum Rated Safe Operating Area



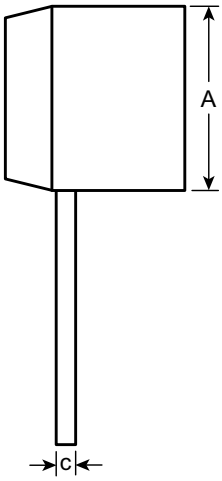
Thermal Response Characteristics



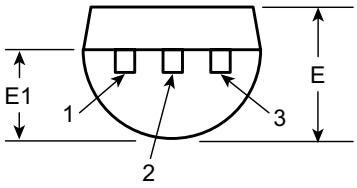
3-Lead TO-92 Package Outline (N3)



Front View



Side View



Bottom View

Symbol		A	b	c	D	E	E1	e	e1	L
Dimensions (inches)	MIN	.170	.014†	.014†	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022†	.022†	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.
** This dimension is not specified in the JEDEC drawing.*
† This dimension differs from the JEDEC drawing.
Drawings not to scale.
***Supertex Doc.#:** DSPD-3TO92N3, Version E041009.*

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to http://www.supertex.com/packaging.html.)

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